

Title (en)
METHOD AND DEVICE FOR RESUMING THE WIRE SAWING PROCESS OF A WORKPIECE AFTER AN UNSCHEDULED INTERRUPTION

Title (de)
VERFAHREN UND VORRICHTUNG ZUR WIEDERAUFNAHME DES DRAHTSÄGEPROZESSES EINES WERKSTÜCKES NACH EINER UNPLANMÄSSIGEN UNTERBRECHUNG

Title (fr)
PROCÉDÉ ET DISPOSITIF DE REPRISE DE PROCESSUS DE SCIAGE PAR SCIE À FIL D'UNE PIÈCE APRÈS UNE INTERRUPTION NON PROGRAMMÉE

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EP 3478437 A1 20190508 (DE)

Application
EP 17735021 A 20170620

Priority
• DE 102016211883 A 20160630
• EP 2017065082 W 20170620

Abstract (en)
[origin: WO2018001793A1] The invention relates to a method for resuming an interrupted process for sawing a workpiece (6) into a plurality of wafers using a wire saw which uses a sawing wire (3), for example a diamond sawing wire, coated with a cutting grain. The method according to the invention is presented here as an example of a process for sawing a workpiece made of a semiconductor material into a plurality of wafers using a diamond wire saw but is also suitable for workpieces made of other materials. The invention additionally relates to a device for sawing a workpiece into a plurality of wafers using a sawing wire, said device allowing the detection of the position of a wire break.

IPC 8 full level
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B23D 57/0023 (2013.01 - EP KR); **B23D 57/0053** (2013.01 - US); **B23D 57/0061** (2013.01 - KR); **B23D 57/0069** (2013.01 - KR); **B28D 5/045** (2013.01 - EP KR US); **B23D 57/0023** (2013.01 - US); **B23D 57/0061** (2013.01 - US); **B23D 57/0069** (2013.01 - US); **B28D 5/0076** (2013.01 - US)

Citation (search report)
See references of WO 2018001793A1

Cited by
CN113521920A

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AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

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